

Amendments to the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims

1. (currently amended) A note such as a banknote or security note, the note comprising a substrate having a zone of reduced substrate thickness, the zone of reduced substrate thickness forming a transparent window in the substrate, wherein the note further comprises reinforcing means to increase the resistance of the zone of reduced substrate thickness.
2. (previously presented) A note as claimed in claim 1, wherein the substrate is made of a paper substrate.
3. (currently amended) A note as claimed in claim 1, wherein the reinforcing means comprise at least a strip of material covering at least the zone of reduced substrate thickness on at least one side of the substrate.
4. (previously presented) A note as claimed in claim 3, wherein the strip of material is a transparent polymer material.
5. (currently amended) A note as claimed in claim 1, wherein the reinforcing means comprise a patch of material covering at least the zone of reduced substrate thickness, the patch being formed by a partially demetallized OVD patch placed on at least one side of the note.
6. (previously presented) A note as claimed in claim 1, wherein the reinforcing means further comprise an additional security feature.
7. (previously presented) A note as claimed in claim 1, wherein the reinforcing means are placed on both sides of the note.

8. (previously presented) A note as claimed in claim 3, wherein the reinforcing means comprise a strip on one side of the substrate and a patch on the other side of the substrate.

9. (previously presented) A sheet of substrate further comprising a plurality of notes as defined in claim 1.

10. (currently amended) A process for producing notes, such as banknotes or security notes, the notes comprising a substrate having a zone of reduced substrate thickness, which zone of reduced substrate thickness forms ~~forming~~ a transparent window in the substrate, the process comprising the step of covering at least the zone of reduced substrate thickness on at least one side of the substrate with reinforcing means in order to increase the resistance of the zone of reduced substrate thickness.

11. (currently amended) A process according to claim 10, wherein it comprises the step of covering the zone of reduced substrate thickness with reinforcing means on both sides of the substrate.

12. (previously presented) A process according to claim 10, wherein the reinforcing means comprise at least a strip or a patch of material.

13. (previously presented) A process according to claim 10, wherein it further comprises the step of providing said reinforcing means with an additional security feature.

14. (new) A note as claimed in claim 1, wherein the zone of reduced substrate thickness is distinct from a through opening.

15. (new) A process according to claim 10, wherein the zone of reduced substrate thickness is distinct from a through opening.